

A B C D E

SPECIFICATIONS:

1.MATERIAL

- HOUSING :THERMOPLASTIC,UL 94V-0 , PA6T,BLACK,HSF
- MODULE CASE : THERMOPLASTIC, UL 94V -0,BLACK,HSF
- RJ CONTACTS :PHOSPHOR BRONZE
- PLATING :SELECT GOLD ON CONTACT AREA (SEE PART NO)
- 100u" MIN TIN PLATING ON SOLDER TAILS,
- 30u" MIN NICKEL OVERALL
- SOLDER TAIL TERMINAL : BRASS
- PLATING:100u" MIN TIN 30u" MIN NICKEL OVERALL
- SHIELD :STAINLESS,THICKNESS=0.2mm,NICKEL PLATED

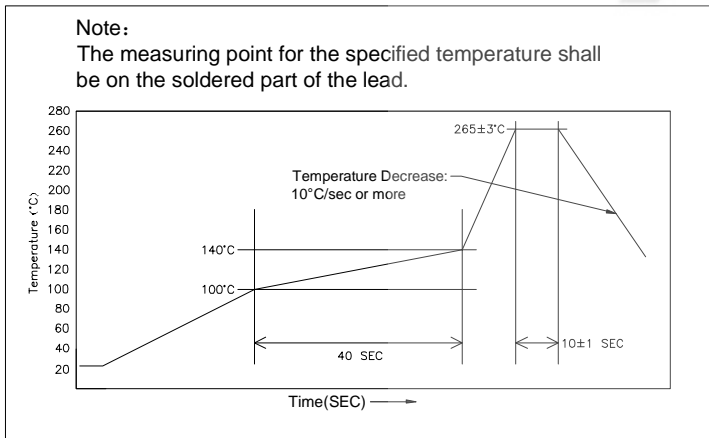
2.RJ45 SPECIFICATIONS

- INSULATION RESISTANCE :500 MOHMS MIN
- INSERTION FORCE WITH THE LATCH DEPRESSED :22N MAX
- REMOVAL FORCE WITH THE LATCH DEPRESSED :44N MAX
- DURABILTY :750 CYCLES

3.OPERATING AND STORAGE TEMPERATURE

- OPERATING TEMPERATURE :0°C TO +70°C
- STORAGE TEMPERATURE :40°C TO +85°C

4.TEMPERATURE CONDITION OF WAVE SOLDERING:



ELECIRICAL CHARACIERISIICS :

1.INSERTION LOSS

- 1~50MHz -0.5dB Max.
- 50~125MHz -1.0dB Max.

2.RETURN LOSS(LOAD 100Ω)

- 1~40MHz -20dB MIN
- 40~200 MHz -20+15*0g(Freq MHz/40MHz)dB MIN

3.REFLECTED CM TO DIFF CONVERSION(REF)

- 10~125 MHz -45+Fre0 MHz/35MHz dB MIN

4.CM TO CM ATTENUATION (REF)

- 30~200MHz -25dB MIN

5.CROSS TALK (REF)

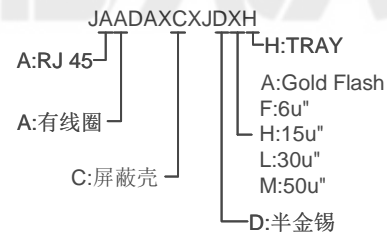
- 1~125MHZ -30dB MIN

6.OCL @ 100KHz , 0.1V.8mA DC BIAS

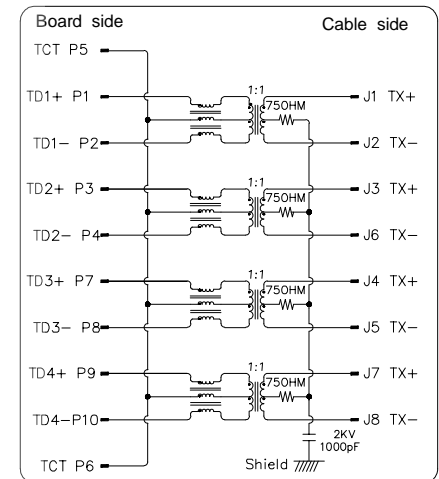
- (P1-P2)(P3-P4),(P7-P8),(P9-P10):160 uH MIN

7.HI-POT TEST

- PCB SIDE TO CABLE SIDE:2250VDC 60S



SCHEMATIC FOR RJ45:



TOLERANCE TABLE	SCALE	1:1	DRAWN	江蒙	DATE	2024/05/28	DWG. NO.	600-0000-2454	TITLE	RJ45 ICM, 2.5G BASE-T, W/O LED CUSTOMER DRAWING	REV.	1
	X. ± 0.30	X.° ± 3°	CHECK	李晨涛	DATE	2024/05/28	PARTS NO.(INTENDED USE)		JAADAXCXJDXH		SHEET	2/2
	.X ± 0.25	.X° ± 2°	APPROVE	朱宁静	DATE	2024/05/28						
	.XX ± 0.20		SIZE	A4								

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